



RECEIVED
APR 22 2003
TECHNOLOGY CENTER 2800
#15/Amo
C
4/25/03
VJ

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Tatsuya ARAO et al.

Serial No. 09/826,416

Filed: April 5, 2001

For: SEMICONDUCTOR DEVICE AND)

MANUFACTURING METHOD)

THEREOF)

Art Unit: 2811

Examiner: T. Tran

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on April 14, 2003.

Eric Robinson

AMENDMENT

Honorable Commissioner of Patents

Washington, D.C. 20231

Sir:

In response to the Official Action dated December 13, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

2. (Amended) A semiconductor device comprising:
- a first wiring and a second wiring formed of a first conductive film on an insulating surface;
 - a second conductive film formed on the first and second wirings so as to correspond thereto;
 - a pair of first semiconductor films of one conductivity type formed on the second conductive film;
 - a second semiconductor film formed on and extending between the pair of first semiconductor films;
 - an insulating film formed on the second semiconductor film; and
 - a third conductive film formed on the insulating film,